Recommended Mounting Pad Dimensions for Thin Film RF Devices

These diagrams show the recommended pad layout dimensions for the AVX Thin Film range of RF/Microwave components.

**ACCU-F® / ACCU-P®**

**WAVE SOLDERING**

**REFLOW SOLDERING**

**ACCU-L 0402, 0603 AND 0805 CASE SIZE**

**WAVE SOLDERING**

**REFLOW SOLDERING**

millimeters (inches)
Recommended Mounting Pad Dimensions for Thin Film RF Devices

THIN FILM DIRECTIONAL COUPLERS

CP0402 LGA

CP0603 LGA

CP0603 SMD

CP0803 SMD

DB0805 SMD

LOW PASS FILTERS

LP0603

millimeters (inches)

LOW PASS FILTERS millimeters (inches)

THIN FILM DIRECTIONAL COUPLERS millimeters (inches)

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